



VMDSEMI

VSTD065R15ANA

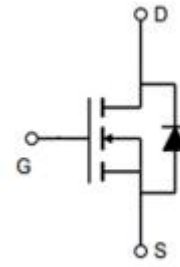
Datasheet



VMDSEMI

General Description
Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
650V	150mΩ@10V	22A



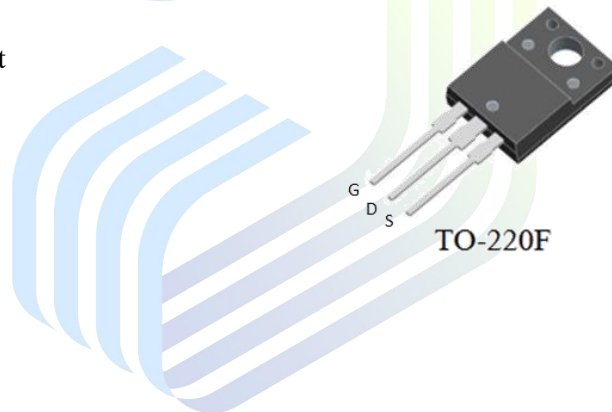
Symbol of VSTD065R15ANA

Features

- Extremely low switching loss
- Excellent stability and uniformity
- RoHS and Halogen-Free Compliant

Application

- PC power
- LED lighting
- Telecom power
- Server power
- Solar/UPS

Package Type


Package Type of VSTD065R15ANA

Ordering Information

Product Name	Package	Marking
VSTD065R15ANA	TO-220F	STD065R15ANA

Absolute Maximum Ratings ($T_A=25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ^{Note 1}	I_D	22	A
Pulsed Drain Current ^{Note 2}	$I_{D, pulse}$	66	A
Continuous Diode Forward Current ^{Note 1}	I_S	22	A
Diode Pulsed Current ^{Note 2}	$I_{S, pulse}$	66	A
Max Power Dissipation ^{Note 3}	P_D	154	W
Avalanche Current, Single Pulse ^{Note 4}	I_{AS}	12.4	A
Avalanche Energy, Single Pulse ^{Note 4}	E_{AS}	769	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\sim 480\text{V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\sim 480\text{V}$, $I_{SD}\leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	-	0.81	-	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient ^{Note 5}	$R_{\theta JA}$	-	62.5	-	

Notes:

Note1: Calculated continuous current based on maximum allowable junction temperature.

Note2: Pulse width limited by safe operating area.

Note3: Based on max. junction temperature, using junction-case thermal resistance.

Note4: $V_{DD}=50\text{V}$, $V_{GS}=10\text{V}$, $L=10\text{mH}$, starting $T_A=25\text{ }^\circ\text{C}$.

Note5: When mounted on 1 inch square copper board, $t\leq 10\text{sec}$. The value in any given application depends on the user's specific board design.

Electrical Characteristics ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650	-	-	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$	-	-	1	μA
Gate-Source Leakage Current	Forward	$I_{GSSF}, V_{GS}=30V, V_{DS}=0V$	-	-	100	nA
	Reverse	$I_{GSSR}, V_{GS}=-30V, V_{DS}=0V$	-	-	-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.8	3.7	4.2	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=14A$	-	123	150	$m\Omega$
Gate Resistance	R_G	$F=1MHz, \text{Open Drain}$	-	4.5	-	Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=50V$	-	2030	-	pF
Output Capacitance	C_{oss}	$V_{GS}=0V$	-	213	-	pF
Reverse Transfer Capacitance	C_{rss}	$f=100kHz$	-	5.54	-	pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=400V$	-	15.79	-	ns
Rise Time	t_r	$I_D=20A$	-	8.65	-	
Turn-off Delay Time	$t_{d(off)}$	$R_G=2\Omega$	-	41.2	-	
Fall Time	t_f	$V_{GS}=10V$	-	6.27	-	
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DS}=400V$ $I_D=14A$ $V_{GS}=0 \text{ to } 10V$	-	11.18	-	nC
Gate to Drain Charge	Q_{gd}		-	14.89	-	
Gate Charge Total	Q_g		-	39.96	-	
Gate Plateau Voltage	$V_{plateau}$		-	5.37	-	V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=1A$	-	0.71	-	V
Reverse Recovery Time	t_{rr}	$V_R=400V$	-	443	-	ns
Reverse Recovery Charge	Q_{rr}	$I_S=20A$	-	6.64	-	μC
Peak Reverse Recovery Current	I_{rrm}	$di/dt=100A/\mu s$	-	30.85	-	A

Electrical Characteristics Diagrams

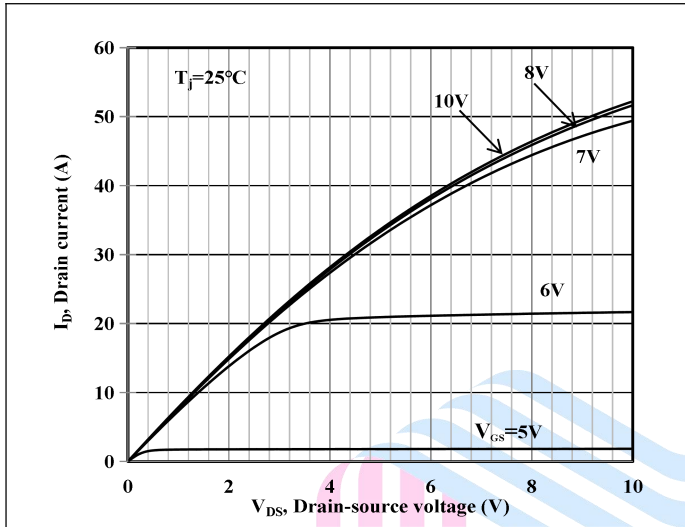


Figure 1. Typ. output characteristics

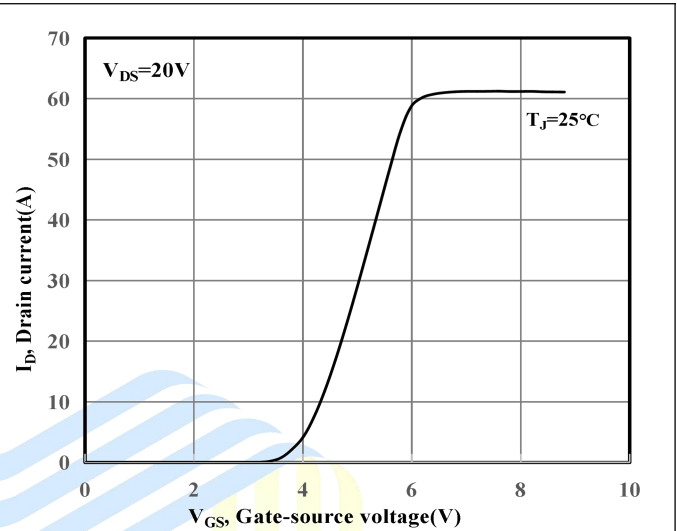


Figure 2. Typ. transfer characteristics

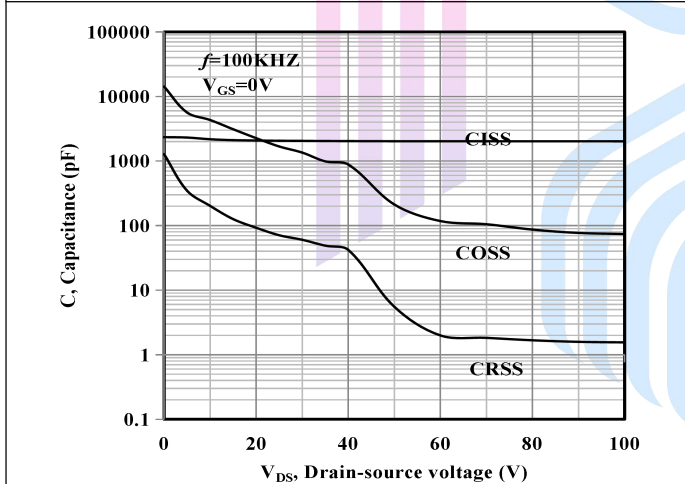


Figure 3. Typ. capacitances

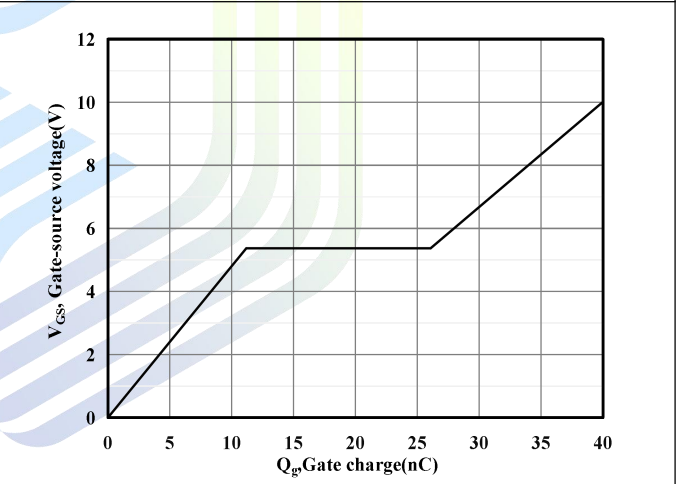


Figure 4. Typ. gate charge

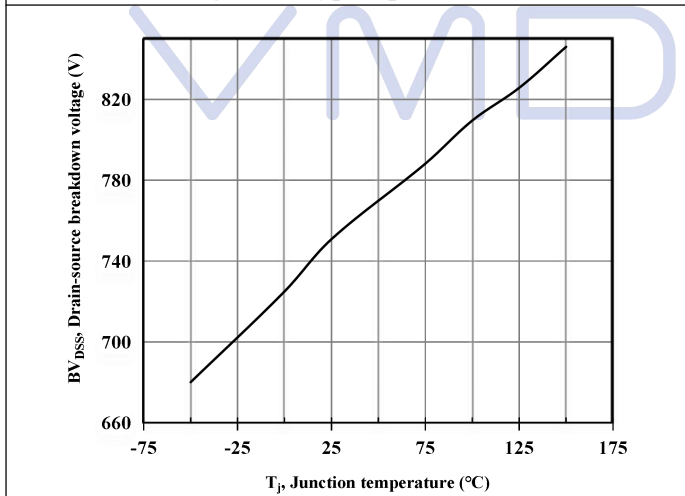


Figure 5. Drain-source breakdown voltage

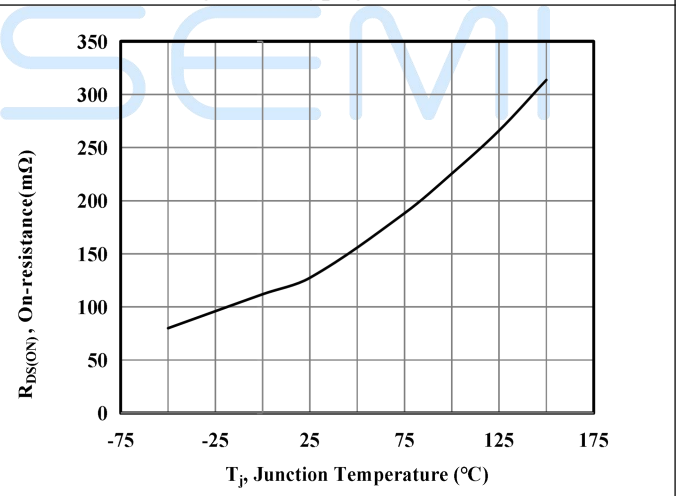
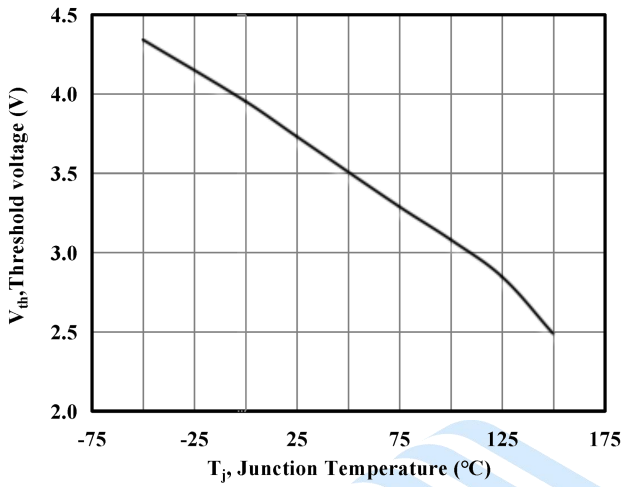
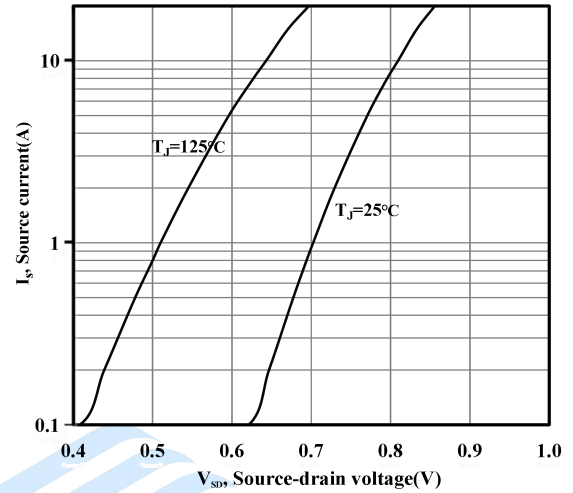
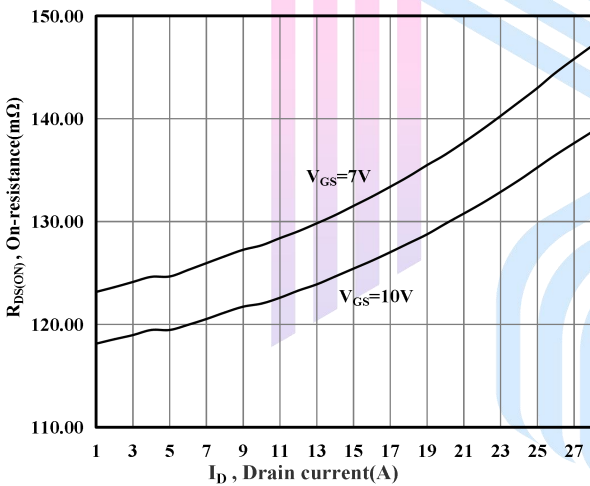
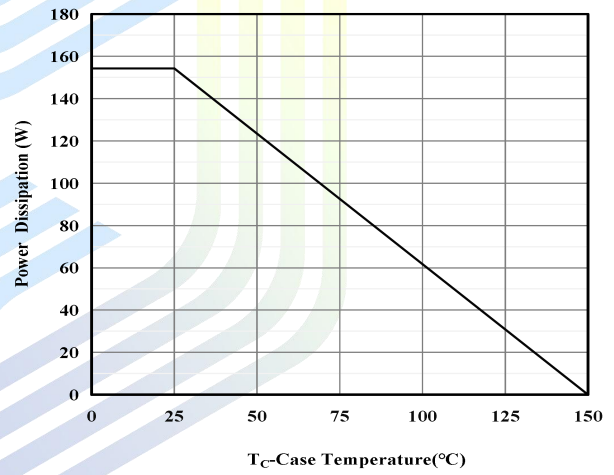
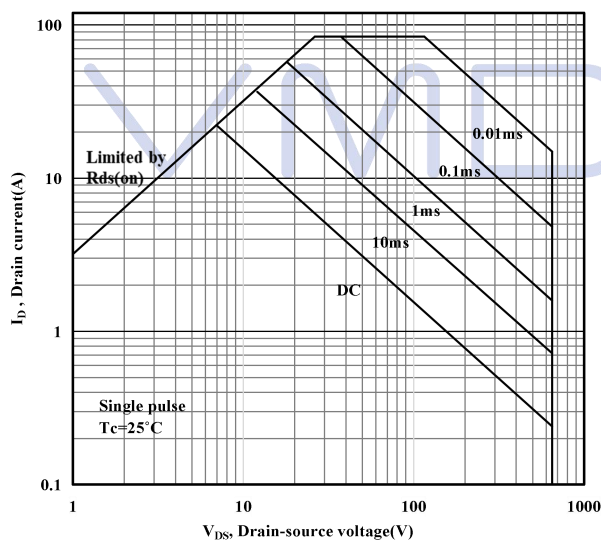
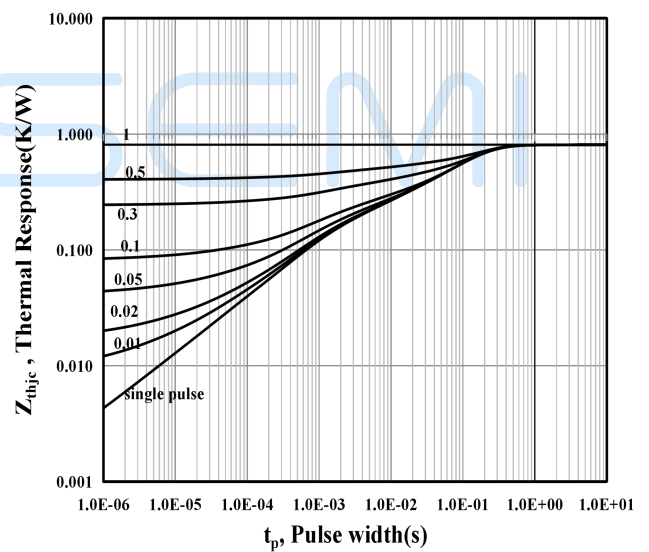
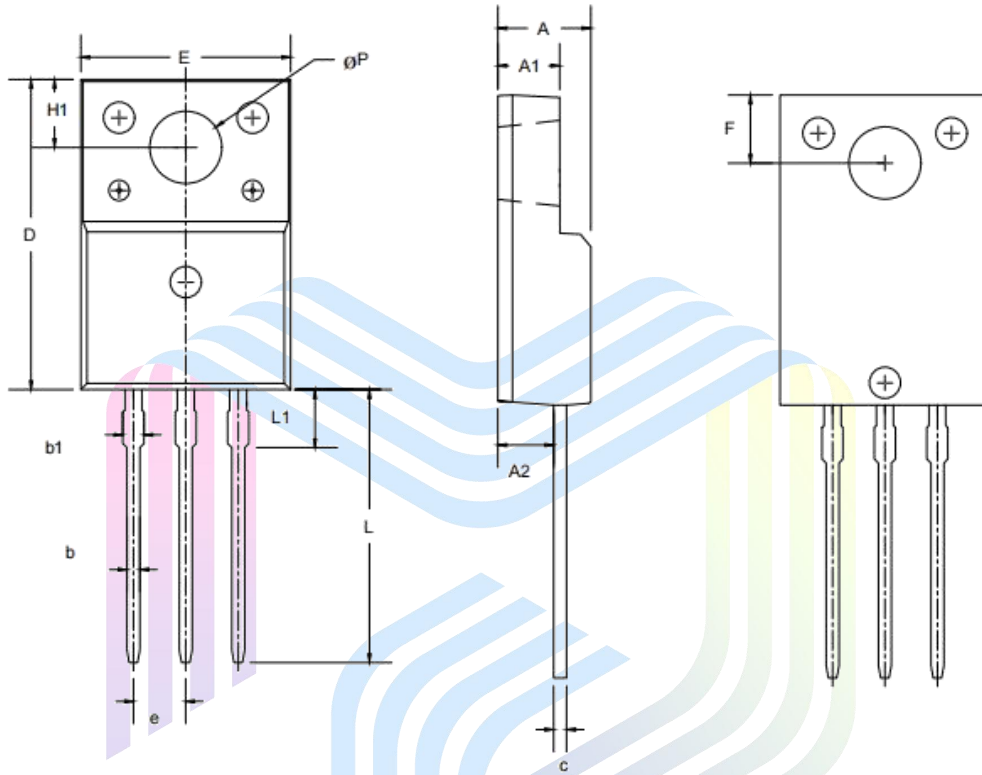


Figure 6. Drain-source on-state resistance


Figure 7. Threshold voltage

Figure 8. Forward characteristic of body diode

Figure 9. Drain-source on-state resistance

Figure 10. Power dissipation

Figure 11. Safe operation area $T_c=25^\circ\text{C}$

Figure 12. Max. transient thermal impedance

Mechanical Dimensions

TO-220F Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	MAX
A	4.50	4.90
A1	2.30	2.80
A2	2.50	2.90
b	0.70	0.95
b1	1.08	1.55
c	0.40	0.70
D	15.00	16.17
E	9.50	10.50
e	2.54BSC	
F	2.80	3.65
H1	6.7REF	
L	12.50	13.50
L1	2.90	3.90
ΦP	2.90	3.40

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